Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	8
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.88 E-01	87.7	877000	57.89	578903
Thermosets	Epoxy Resin	Proprietary	1.64 E-02	5.0	50000	3.30	33005
Thermosets	Phenol Resin	Proprietary	1.64 E-02	5.0	50000	3.30	33005
Thermosets	Epoxy Cresol Novolac	29690-82-2	6.57 E-03	2.0	20000	1.32	13202
Other inorganic materials	Carbon Black	1333-86-3	9.85 E-04	0.3	3000	0.20	1980
Subtotal			3.28 E-01	100	1000000	66.01	660094

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.49 E-01	97.50	975000	29.98	299816
Copper & its alloys	Iron	7439-89-6	3.60 E-03	2.35	23500	0.72	7226
Copper & its alloys	Zinc	7440-66-6	1.84 E-04	0.12	1200	0.04	369
Copper & its alloys	Phosphorus	7723-14-0	4.59 E-05	0.03	300	0.01	92
Subtotal			1.53 E-01	100.00	1000000	30.75	307504

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.55 E-03	100.0	1000000	0.31	3106

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.07 E-02	100.0	1000000	2.16	21577

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.60 E-04	99.99	1000000	0.05	523

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.50 E-03	100.0	1000000	0.50	5025

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.20 E-04	80	800000	0.14	1447
Thermosets	Epoxy Resin	Proprietary	1.35 E-04	15	150000	0.03	271
Others	Curing agent & hardener	Proprietary	4.50 E-05	5	50000	0.01	90
Subtotal			9.00 E-04	100	1000000	0.18	1809

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.09 E-04	60.4	604000	0.022	219
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	5.04 E-05	28.0	280000	0.010	101
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.80 E-05	10.0	100000	0.004	36
Other organic materials	Ethylbenzene	100-41-4	1.80 E-06	1.0	10000	0.00036	4
Other organic materials	Xylene	1330-20-7	1.08 E-06	0.6	6000	0.00022	2.2
Subtotal			1.80 E-04	100.0	1000000	0.04	362

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.98 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	8
Terminal Finish	85Sn15Pb

Environmental Compliance Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.88 E-01	87.7	877000	57.89	578903
Thermosets	Epoxy Resin	Proprietary	1.64 E-02	5.0	50000	3.30	33005
Thermosets	Phenol Resin	Proprietary	1.64 E-02	5.0	50000	3.30	33005
Thermosets	Epoxy Cresol Novolac	29690-82-2	6.57 E-03	2.0	20000	1.32	13202
Other inorganic materials	Carbon Black	1333-86-3	9.85 E-04	0.3	3000	0.20	1980
Subtotal			3.28 E-01	100	1000000	66.01	660094

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.49 E-01	97.50	975000	29.98	299816
Copper & its alloys	Iron	7439-89-6	3.60 E-03	2.35	23500	0.72	7226
Copper & its alloys	Zinc	7440-66-6	1.84 E-04	0.12	1200	0.04	369
Copper & its alloys	Phosphorus	7723-14-0	4.59 E-05	0.03	300	0.01	92
Subtotal			1.53 E-01	100.00	1000000	30.75	307504

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.55 E-03	100.0	1000000	0.31	3106

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.12 E-03	85.0	850000	1.83	18341
Tin & its alloys	Lead	7439-92-1	1.61 E-03	15.0	150000	0.32	3237
Subtotal			1.07 E-02	100.0	1000000	2.16	21577

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.60 E-04	99.99	1000000	0.05	523

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.50 E-03	100.0	1000000	0.50	5025

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.20 E-04	80	800000	0.14	1447
Thermosets	Epoxy Resin	Proprietary	1.35 E-04	15	150000	0.03	271
Others	Curing agent & hardener	Proprietary	4.50 E-05	5	50000	0.01	90
Subtotal			9.00 E-04	100	1000000	0.18	1809

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.09 E-04	60.4	604000	0.022	219
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	5.04 E-05	28.0	280000	0.010	101
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.80 E-05	10.0	100000	0.004	36
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Other organic materials	Xylene	1330-20-7	1.08 E-06	0.6	6000	0.00022	2.2
Subtotal			1.80 E-04	100.0	1000000	0.04	362

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.98 E-01**	**100.00**	**1000000**

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ANALOG DEVICES

ADI Proprietary